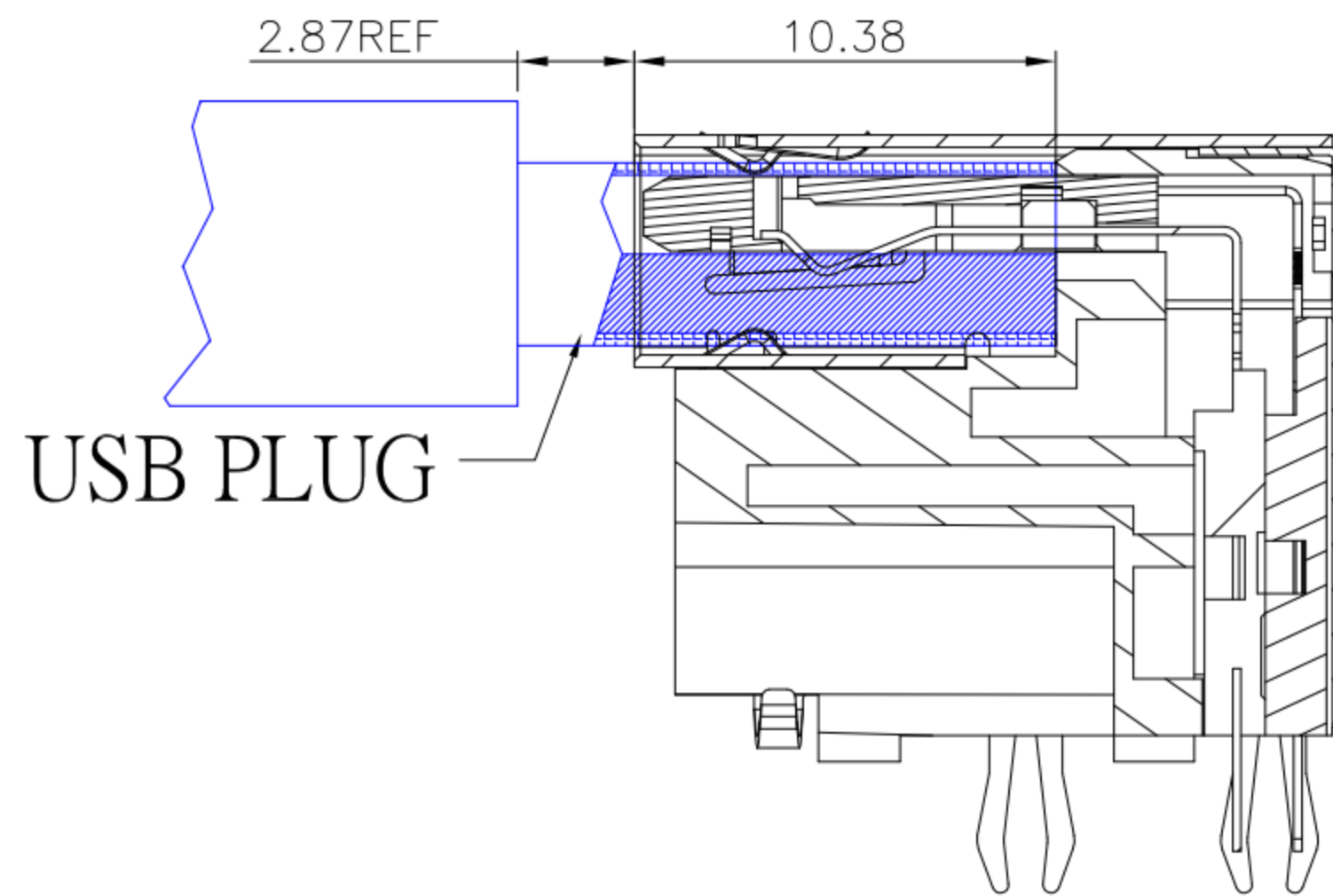
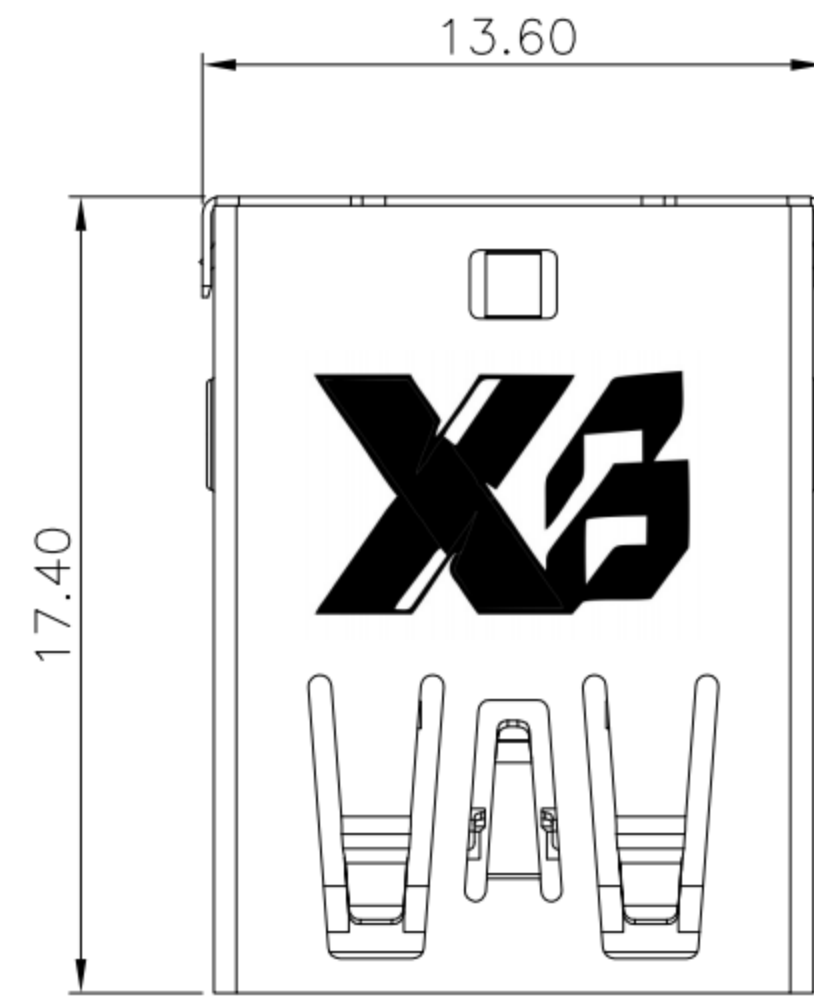
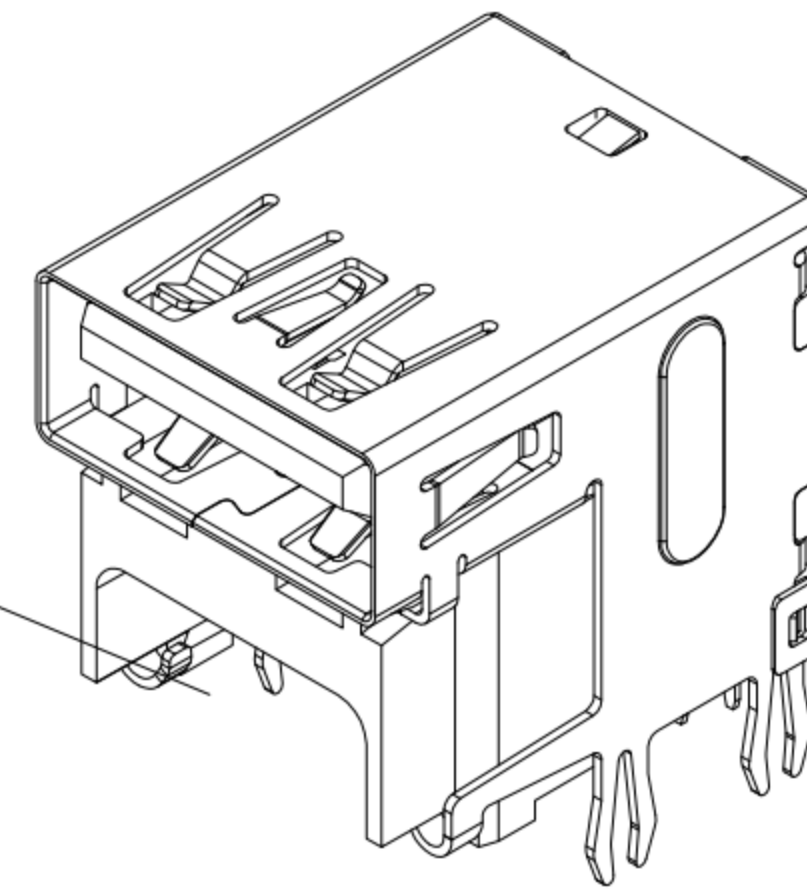
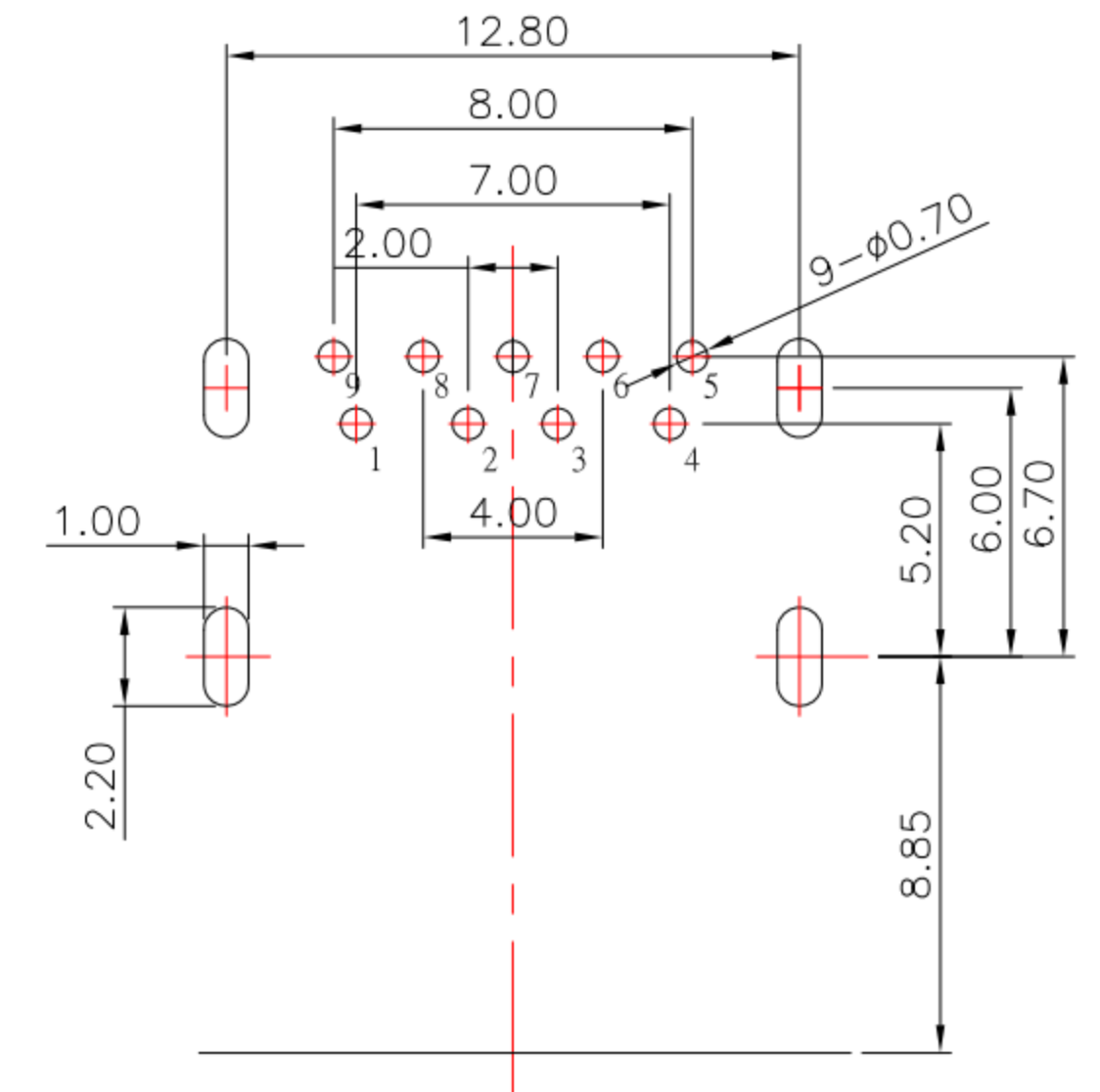




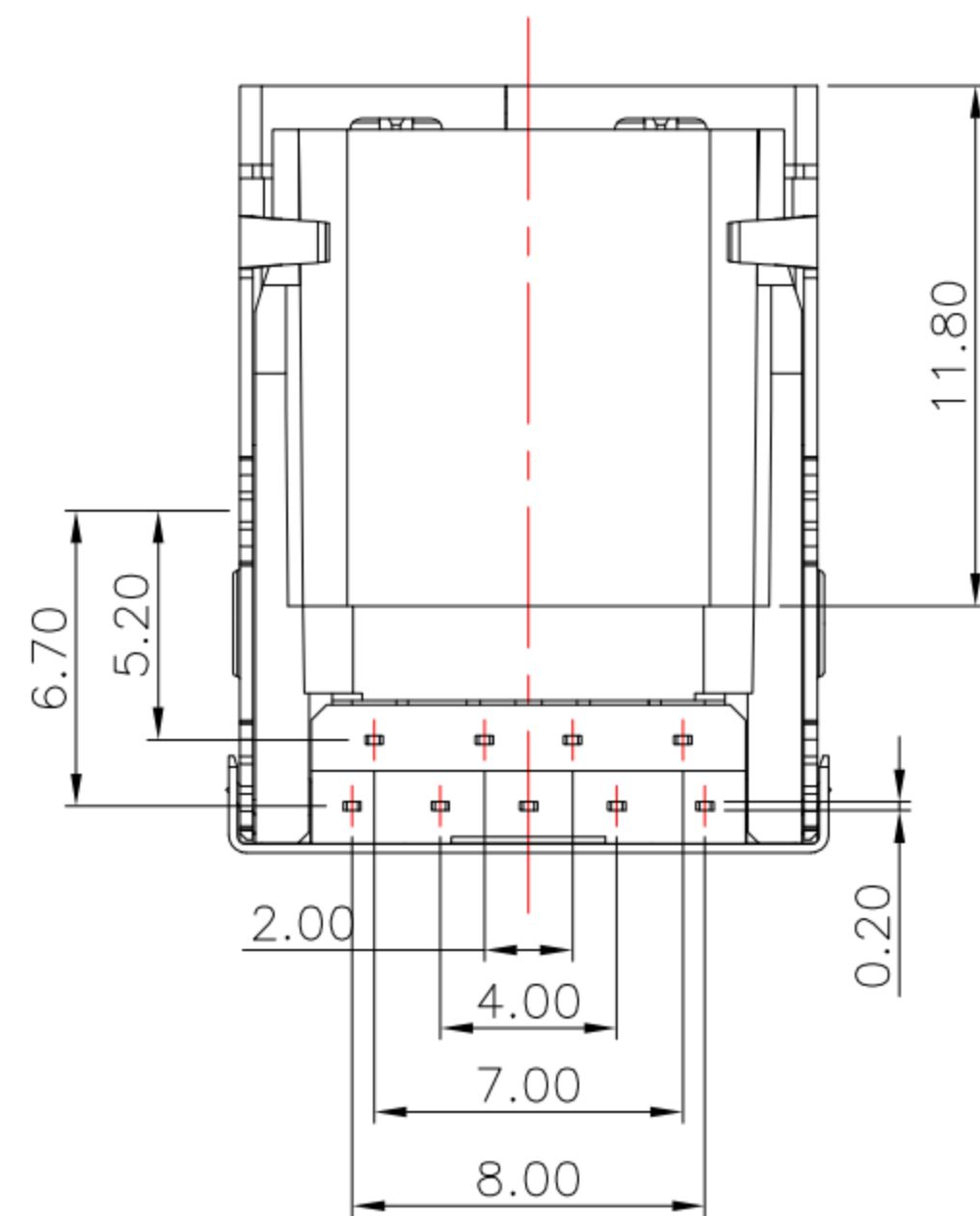
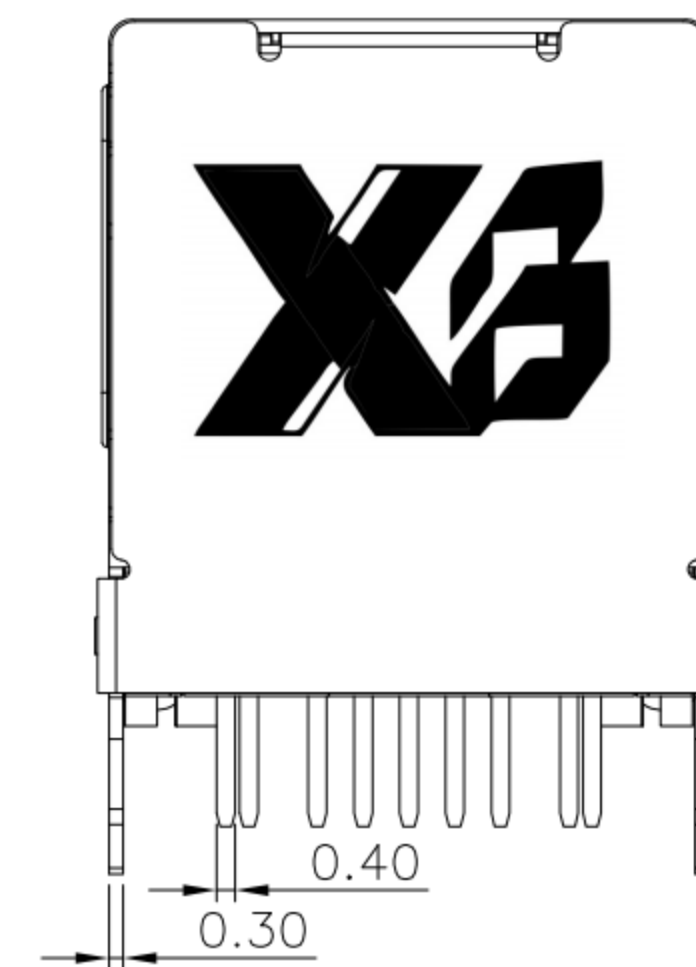
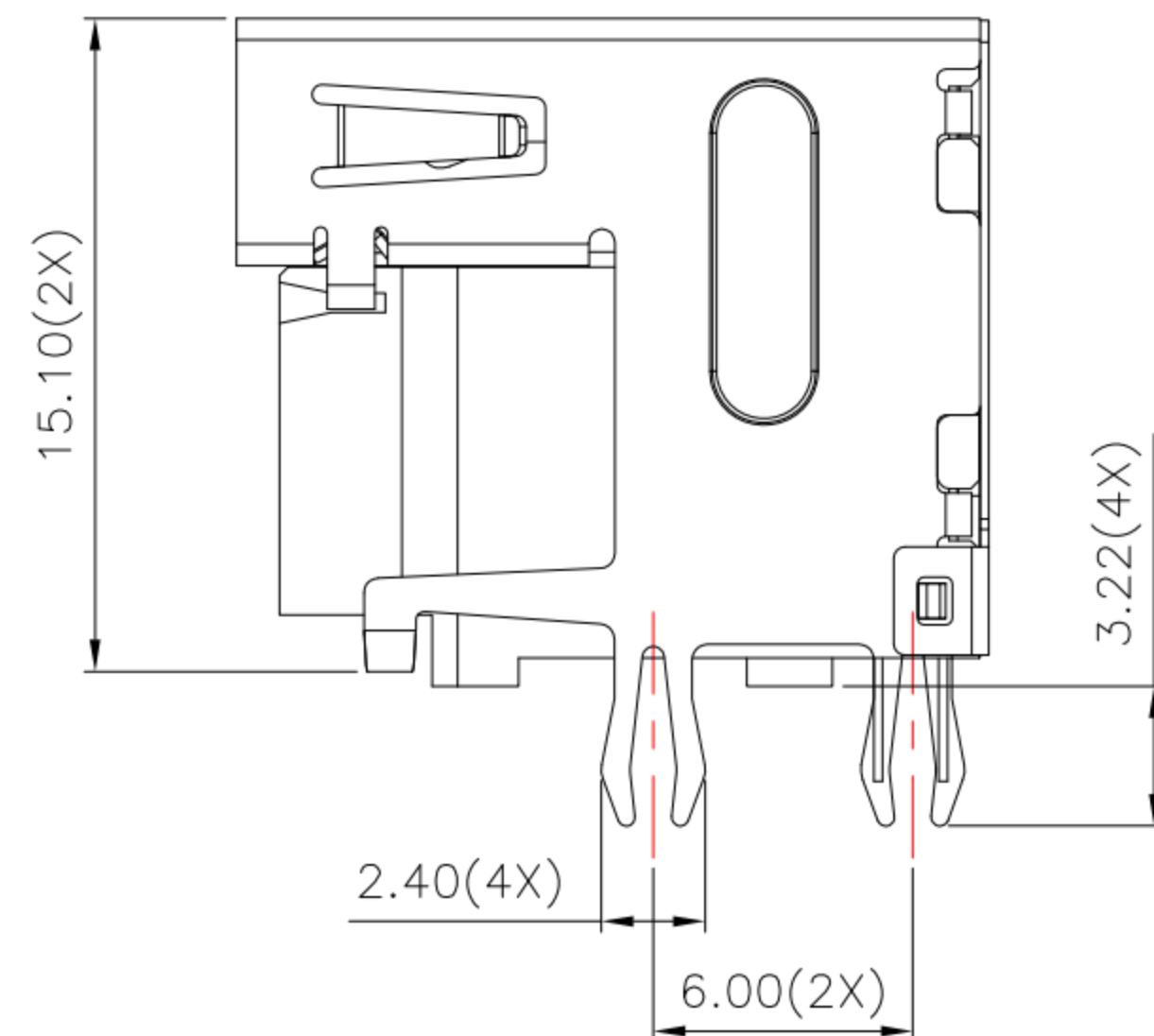
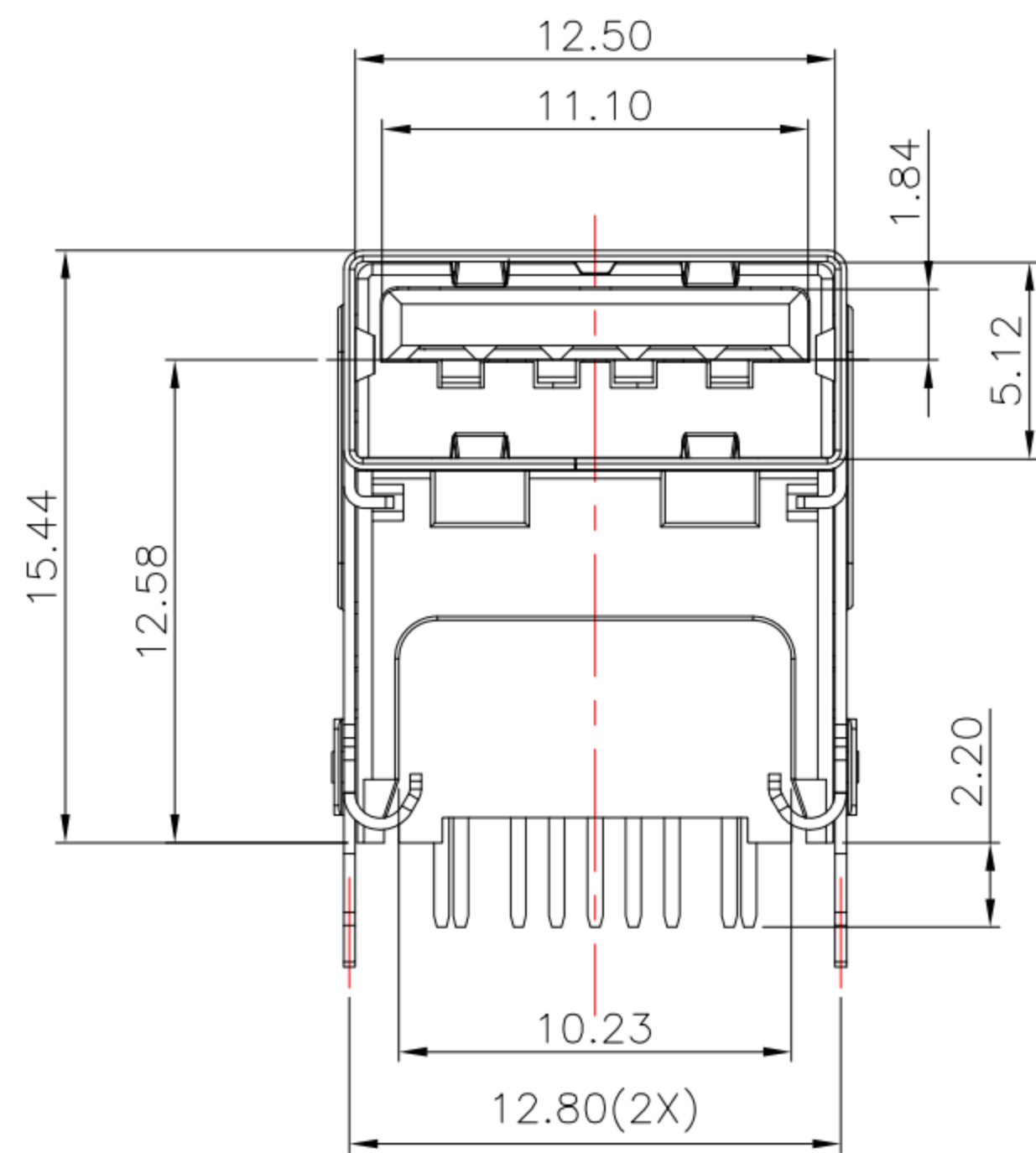
Type C 放置位置



USB 3.0 AF 架高型的下方空間是擺放Type C connector, 先打件Type C connector ,再打件USB 3.0 AF



RECOMMENDED PCB LAYOUT



SUA-110H13-30xx-S277

鍍層厚度:

Blank : 1u"
2 : 15u"
3 : 30u"

COLOR :

BLUE : Blank
Black : B
Red : R

Contact Number	Signal Name
PIN1	VBUS
PIN2	D-
PIN3	D+
PIN4	GND
PIN5	StdA_SSRX-
PIN6	StdA_SSRX+
PIN7	GND_DRAIN
PIN8	StdA_SSTX-
PIN9	StdA_SSTX+
Shell	Shield

NOTE:

1.MATERIAL:

1.1 Housing: PA66

1.2 Contact: PHOSPHOR BRONZE

1.3 Shell: SUS

2.Finish:

2.1 Contact: Plated Gold in Mating Area ;

Tin Plated on Solder Balls ;

Nickel under plated overall

2.2 Shell: Nickel under Plated surface layer

3.SPECIFICATION:

3.1 Current Rate: 1.8 A

3.2 insulator Resistance:100MΩ Min

3.3 Dielectric Strength: 500V AC

3.4 Contact Resistance: 30mΩ Max

3.5 Operation Temperature: -40°C ~ +85°C

3.6 Insertion Force: 35 N

3.7 Extraction Force: 10 N



TOLERANCE UNLESS OTHERWISE STATED :	Up to 5 ±0.2 Above 5 ~ 15 ±0.3 Above 15 ~ 30 ±0.4 Above 30 ~ 50 ±0.5 Angle ±0.3°	3RD. ANGEL'S	UNITS	MM
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DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	11/26/21	FINISH	MODLE	USB AF DIP 架高 CH=12.58mm
CHECKED BY:	DATE	SCALE	DWG NO.	SUA-110H13-30xx-S277
Jacky Chen	11/26/21	1 : 1	PART NO.	SUA-110H13-30xx-S277
APPROVED BY:	DATE	SHEET NO.	1 of 1	SIZE A4
Tony Kao	11/26/21			VER R1

1	新增產品說明和更新材質	Jack	112621
ITEM NO.	DESCRIPTION	DRAWN	DATE